

IN THE CLAIMS

1. (Currently amended) A package, comprising:

a substrate with an inner surface to which a die is to be attached, forming electrical connections through the substrate, between the die and the exterior of the package;

a lid with an inner surface facing the inner surface of the substrate;

thermal attach disposed between the die and the inner surface of the lid;

and

sealant disposed between the substrate and the lid to bond the lid to the substrate, wherein the sealant is disposed in a pattern with at least one break in the pattern, with the at least one break in the pattern remaining subsequent to the substrate and lid being assembled together.

2. (Original) The apparatus of claim 1, wherein the package is a ball grid array package.

3. (Original) The apparatus of claim 1, wherein the package is a pin grid array package.

4. (Cancelled)

5. (Original) The apparatus of claim 1, wherein a vent-hole is formed through the lid.

6. (Original) The apparatus of claim 1, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with the at least one break.
7. (Original) The apparatus of claim 6, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.
8. (Original) The apparatus of claim 7, wherein the four breaks comprise a minimum of 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
9. (Original) The apparatus of claim 6, wherein the rectangular pattern has four breaks, one in each corner of the substantially rectangular pattern.
10. (Original) The apparatus of claim 9, wherein the four breaks comprise a minimum of 10% of the total length of what would otherwise be an unbroken substantially rectangular pattern.
11. (Original) The apparatus of claim 1, wherein the substrate is susceptible to absorbing moisture, and the pressure existing between the substrate and the lid is as a result of moisture being released within the package by the substrate and being converted to steam.
12. (Original) The apparatus of claim 11, wherein the substrate is comprised of organic material.
13. (Original) The package of claim 1, wherein the die is attached to the substrate using a controlled collapsed chip connection.

14. (Cancelled)

15-22. (Withdrawn)

23. (Currently Amended) An apparatus, comprising:

a substrate with an inner surface;

a lid with an inner surface facing the inner surface of the substrate;

a die on which electronic circuitry is disposed, enclosed between the substrate and the lid, and attached to the inner surface of the substrate which provides electrical connections between the die and the exterior of the package;

thermal attach disposed between the die and inner surface of the lid; and

sealant disposed between the substrate and the lid to bond the lid to the substrate, wherein the sealant is disposed in a pattern with at least one break in the pattern, with the at least one break in the pattern remaining subsequent to the substrate and lid being assembled together.

24. (Cancelled)

25. (Original) The apparatus of claim 23, wherein the pattern in which the sealant is disposed between the lid and the substrate is a substantially rectangular pattern with the at least one break.

26. (Original) The apparatus of claim 25, wherein the rectangular pattern has four breaks, one in each side of the substantially rectangular pattern.

27. (Previously Amended) The apparatus of claim 23, wherein the die is attached to the substrate using a controlled collapsed chip connection.